

U.S. Patent Application Serial No. 10/087,913

PRELIMINARY AMENDMENT

TO RCE filed September 16, 2004

**AMENDMENTS TO THE SPECIFICATION:**

Page 4, please replace the paragraph starting in line 22 with the following amended paragraph:

In this invention, however, only a high-temperature process is disclosed as a specific process, where, for example, it is necessary to realize a temperature as high as the melting point [(221 °C)] (about 231 °C) or above of tin in order to melt tin used as a coating metal, while it is also necessary to effect heat treatment at 300 to 400 °C in order to cure the thermosetting resin. Accordingly, it is difficult therewith to avoid the problem of thermal damage to substrates, LSI's, and materials peripheral thereto.